

MC74LVX541

Octal Bus Buffer

The MC74LVX541 is an advanced high speed CMOS octal bus buffer fabricated with silicon gate CMOS technology. It achieves high speed operation similar to equivalent Bipolar Schottky TTL while maintaining CMOS low power dissipation.

The MC74LVX541 is a noninverting type. When either $\overline{OE1}$ or $\overline{OE2}$ are high, the terminal outputs are in the high impedance state.

The internal circuit is composed of three stages, including a buffer output which provides high noise immunity and stable output. The inputs tolerate voltages up to 7 V, allowing the interface of 5 V systems to 3 V systems.

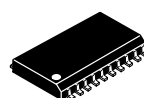
- High Speed: $t_{PD} = 5.0$ ns (Typ) at $V_{CC} = 3.3$ V
- Low Power Dissipation: $I_{CC} = 4$ μ A (Max) at $T_A = 25^\circ$ C
- High Noise Immunity: $V_{NIH} = V_{NIL} = 28\%$ V_{CC}
- Power Down Protection Provided on Inputs
- Balanced Propagation Delays
- Designed for 2 V to 3.6 V Operating Range
- Low Noise: $V_{OLP} = 1.2$ V (Max)
- Pin and Function Compatible with Other Standard Logic Families
- Latchup Performance Exceeds 300 mA
- ESD Performance: HBM > 2000 V; Machine Model > 200 V
- Chip Complexity: 134 FETs or 33.5 Equivalent Gates



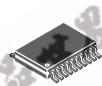
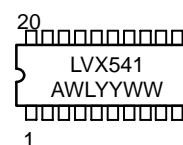
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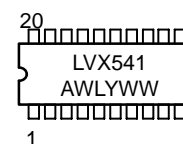
MARKING DIAGRAMS



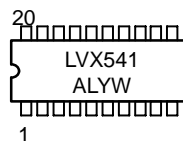
SOIC-20
DW SUFFIX
CASE 751D



TSSOP-20
DT SUFFIX
CASE 948E



SOIC EIAJ-20
M SUFFIX
CASE 967



A = Assembly Location

WL = Wafer Lot

YY = Year

WW = Work Week

A = Assembly Location

WL = Wafer Lot

Y = Year

WW = Work Week

A = Assembly Location

L = Wafer Lot

Y = Year

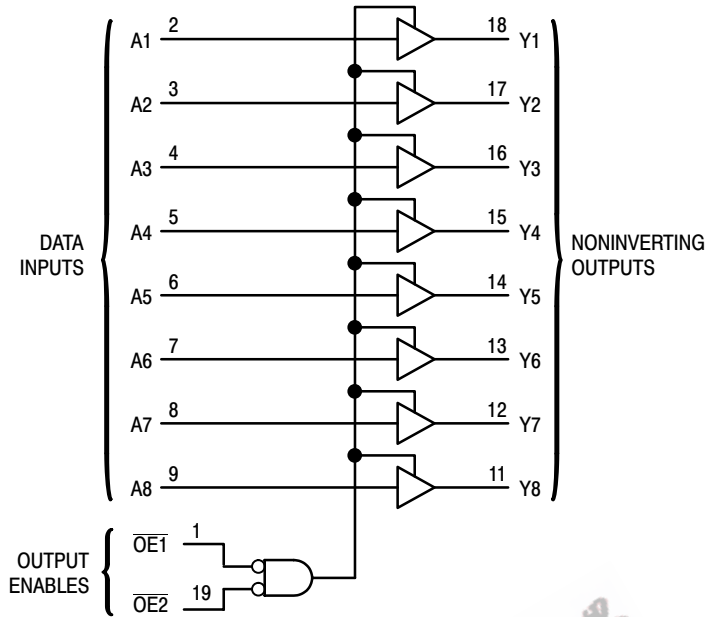
W = Work Week

ORDERING INFORMATION

| Device | Package | Shipping |
|----------------|-----------------|-----------------|
| MC74LVX541DW | SOIC-20 | 38 Units/Rail |
| MC74LVX541DT | TSSOP-20 | 75 Units/Rail |
| MC74LVX541DTR2 | TSSOP-20 | 2500 Units/Reel |
| MC74LVX541M | SOIC EIAJ-20 | 40 Units/Rail |
| MC74LVX541MEL | SOIC EIAJ-20 | 2000 Units/Reel |

MC74LVX541

LOGIC DIAGRAM



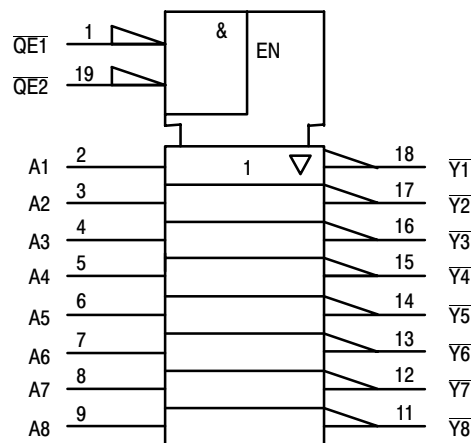
PIN ASSIGNMENT

| | | | |
|-----|-----|----|-----------------|
| OE1 | 1 ● | 20 | V _{CC} |
| A1 | 2 | 19 | OE2 |
| A2 | 3 | 18 | Y1 |
| A3 | 4 | 17 | Y2 |
| A4 | 5 | 16 | Y3 |
| A5 | 6 | 15 | Y4 |
| A6 | 7 | 14 | Y5 |
| A7 | 8 | 13 | Y6 |
| A8 | 9 | 12 | Y7 |
| GND | 10 | 11 | Y8 |

FUNCTION TABLE

| Inputs | | | Output Y |
|--------|-----|---|----------|
| OE1 | OE2 | A | |
| L | L | L | L |
| L | L | H | H |
| H | X | X | Z |
| X | H | X | Z |

IEC LOGIC DIAGRAM



MC74LVX541

MAXIMUM RATINGS*

| Symbol | Parameter | Value | Unit |
|------------------|--|--------------------------------|------|
| V _{CC} | DC Supply Voltage | - 0.5 to + 7.0 | V |
| V _{in} | DC Input Voltage | - 0.5 to + 7.0 | V |
| V _{out} | DC Output Voltage | - 0.5 to V _{CC} + 0.5 | V |
| I _{IK} | Input Diode Current | - 20 | mA |
| I _{OK} | Output Diode Current | ± 20 | mA |
| I _{out} | DC Output Current, per Pin | ± 25 | mA |
| I _{CC} | DC Supply Current, V _{CC} and GND Pins | ± 50 | mA |
| P _D | Power Dissipation in Still Air, SOIC Packages† TSSOP Package† | 500 450 | mW |
| T _{stg} | Storage Temperature | - 65 to + 150 | °C |

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range GND ≤ (V_{in} or V_{out}) ≤ V_{CC}. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

* Absolute maximum continuous ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute-maximum-rated conditions is not implied.

† Derating — SOIC Packages: - 7 mW/°C from 65° to 125°C
TSSOP Package: - 6.1 mW/°C from 65° to 125°C

RECOMMENDED OPERATING CONDITIONS

| Symbol | Parameter | Min | Max | Unit |
|---------------------------------|---|-----|-----------------|------|
| V _{CC} | DC Supply Voltage | 2.0 | 3.6 | V |
| V _{in} | DC Input Voltage | 0 | 5.5 | V |
| V _{out} | DC Output Voltage | 0 | V _{CC} | V |
| T _A | Operating Temperature, All Package Types | -40 | + 85 | °C |
| t _r , t _f | Input Rise and Fall Time V _{CC} = 3.3V ± 0.3V | 0 | 100 | ns/V |

DC ELECTRICAL CHARACTERISTICS

| Symbol | Parameter | Test Conditions | V _{CC} V | T _A = 25°C | | | T _A = - 40 to 85°C | | Unit |
|-----------------|---|--|----------------------|-----------------------|-----|------|-------------------------------|------|------|
| | | | | Min | Typ | Max | Min | Max | |
| V _{IH} | Minimum High-Level Input Voltage | | 2.0 | 1.50 | | | 1.50 | | V |
| | | | 3.0 | 2.0 | | 2.0 | | | |
| | | | 3.6 | 2.4 | | 2.4 | | | |
| V _{IL} | Maximum Low-Level Input Voltage | | 2.0 | | | 0.50 | | 0.50 | V |
| | | | 3.0 | | | 0.80 | | 0.80 | |
| | | | 3.6 | | | 0.80 | | 0.80 | |
| V _{OH} | Minimum High-Level Output Voltage V _{in} = V _{IH} or V _{IL} | I _{OH} = - 50 μA I _{OH} = - 50 μA I _{OH} = - 4 mA | 2.0 | 1.9 | 2.0 | | 1.9 | | V |
| | | | 3.0 | 2.9 | 3.0 | | 2.9 | | |
| | | | 3.0 | 2.58 | | | 2.48 | | |
| V _{OL} | Maximum Low-Level Output Voltage V _{in} = V _{IH} or V _{IL} | I _{OL} = 50 μA I _{OL} = 50 μA I _{OL} = 4 mA | 2.0 | | 0.0 | 0.1 | | 0.1 | V |
| | | | 3.0 | | 0.0 | 0.1 | | 0.1 | |
| | | | 3.0 | | | 0.36 | | 0.44 | |

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DC ELECTRICAL CHARACTERISTICS

| Symbol | Parameter | Test Conditions | V _{CC} V | T _A = 25°C | | | T _A = -40 to 85°C | | Unit |
|-----------------|-------------------------------------|---|----------------------|-----------------------|-----|-----------|------------------------------|------|------|
| | | | | Min | Typ | Max | Min | Max | |
| I _{in} | Maximum Input Leakage Current | V _{in} = 5.5 V or GND | 0 to 3.6 | | | ±0.1 | | ±1.0 | μA |
| I _{OZ} | Maximum Three-State Leakage Current | V _{in} = V _{IL} or V _{IH} V _{out} = V _{CC} or GND | 3.6 | | | ±0.2 5 | | ±2.5 | μA |
| I _{CC} | Maximum Quiescent Supply Current | V _{in} = V _{CC} or GND | 3.6 | | | 4.0 | | 40.0 | μA |

AC ELECTRICAL CHARACTERISTICS (Input t_r = t_f = 3.0 ns)

| Symbol | Parameter | Test Conditions | T _A = 25°C | | | T _A = -40 to 85°C | | Unit |
|--|--|--|-----------------------|------------|--------------|------------------------------|--------------|------|
| | | | Min | Typ | Max | Min | Max | |
| t _{PLH} , t _{PHL} | Maximum Propagation Delay, A to Y | V _{CC} = 2.7 V C _L = 15 pF C _L = 50 pF | | 5.0 7.5 | 7.0 10.5 | 1.0 1.0 | 8.5 12.0 | ns |
| | | V _{CC} = 3.3 ± 0.3 V C _L = 15 pF C _L = 50 pF | | 3.5 5.0 | 5.0 7.0 | 1.0 1.0 | 6.0 8.0 | |
| t _{PZL} , t _{PZH} | Output Enable Time, OE to Y | V _{CC} = 2.7 V C _L = 15 pF R _L = 1 kΩ C _L = 50 pF | | 6.8 9.3 | 10.5 14.0 | 1.0 1.0 | 12.5 16.0 | ns |
| | | V _{CC} = 3.3 ± 0.3 V C _L = 15 pF R _L = 1 kΩ C _L = 50 pF | | 4.7 6.2 | 7.2 9.2 | 1.0 1.0 | 8.5 10.5 | |
| t _{PLZ} , t _{PHZ} | Output Disable Time, OE to Y | V _{CC} = 2.7 V C _L = 50 pF R _L = 1 kΩ | | 11.2 | 15.4 | 1.0 | 17.5 | ns |
| | | V _{CC} = 3.3 ± 0.3 V C _L = 50 pF R _L = 1 kΩ | | 6.0 | 8.8 | 1.0 | 10.0 | |
| t _{OSLH} , t _{OSHL} | Output to Output Skew | V _{CC} = 2.7 V C _L = 50 pF (Note 1) | | | 1.5 | | 1.5 | ns |
| | | V _{CC} = 3.3 ± 0.3 V C _L = 50 pF (Note 1) | | | 1.0 | | 1.0 | ns |
| C _{in} | Maximum Input Capacitance | | | 4.0 | 10 | | 10 | pF |
| C _{out} | Maximum Three-State Output Capacitance (Output in High Impedance State) | | | 6.0 | | | | pF |

| C _{PD} | Power Dissipation Capacitance (Note 2) | Typical @ 25°C, V _{CC} = 5.0V | | | pF |
|-----------------|--|--|-----|-----|----|
| | | Min | Typ | Max | |
| | | | 18 | | |

- Parameter guaranteed by design. t_{OSLH} = |t_{PLHm} - t_{PLHn}|; t_{OSHL} = |t_{PHLm} - t_{PHLn}|.
- C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}/8 (per bit). C_{PD} is used to determine the no-load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

NOISE CHARACTERISTICS (Input t_r = t_f = 3.0 ns, C_L = 50 pF, V_{CC} = 3.3 V)

| Symbol | Parameter | T _A = 25°C | | Unit |
|------------------|--|-----------------------|------|------|
| | | Typ | Max | |
| V _{OLP} | Quiet Output Maximum Dynamic V _{OL} | 0.5 | 0.8 | V |
| V _{OLV} | Quiet Output Minimum Dynamic V _{OL} | -0.5 | -0.8 | V |
| V _{IHD} | Minimum High Level Dynamic Input Voltage | | 2.0 | V |
| V _{ILD} | Maximum Low Level Dynamic Input Voltage | | 0.8 | V |

MC74LVX541

SWITCHING WAVEFORMS

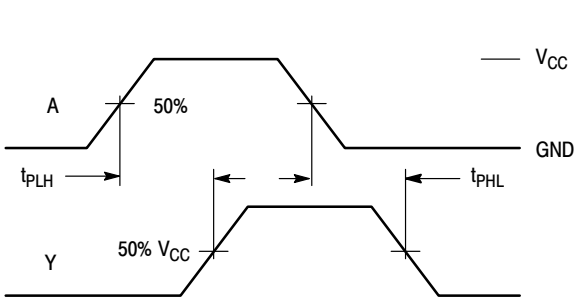


Figure 1.

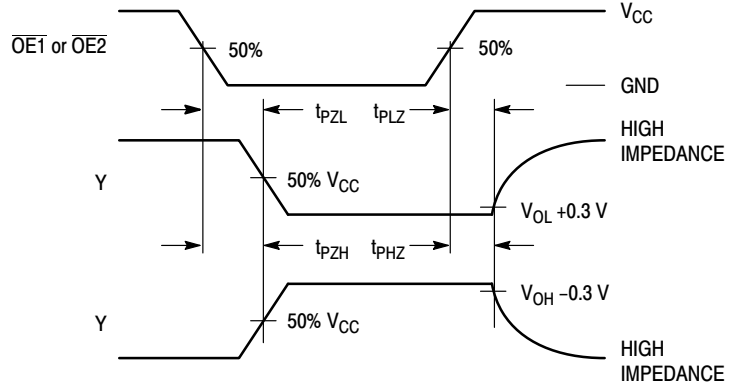
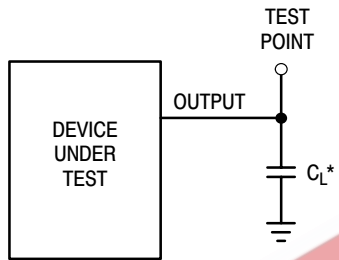


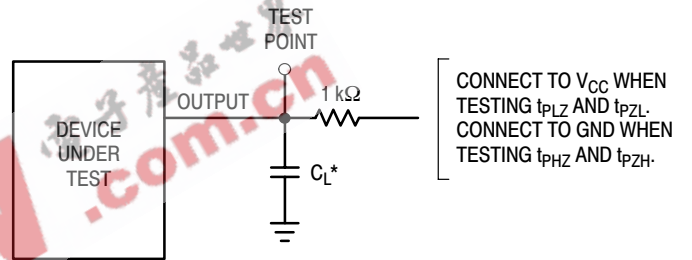
Figure 2.

TEST CIRCUITS



*Includes all probe and jig capacitance

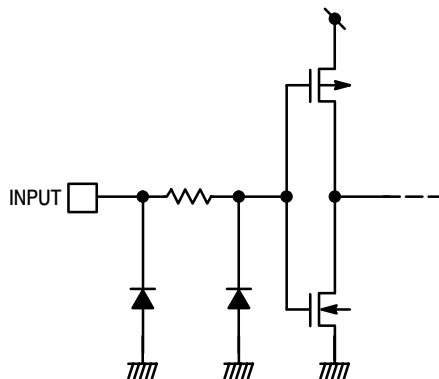
Figure 3.



*Includes all probe and jig capacitance

Figure 4.

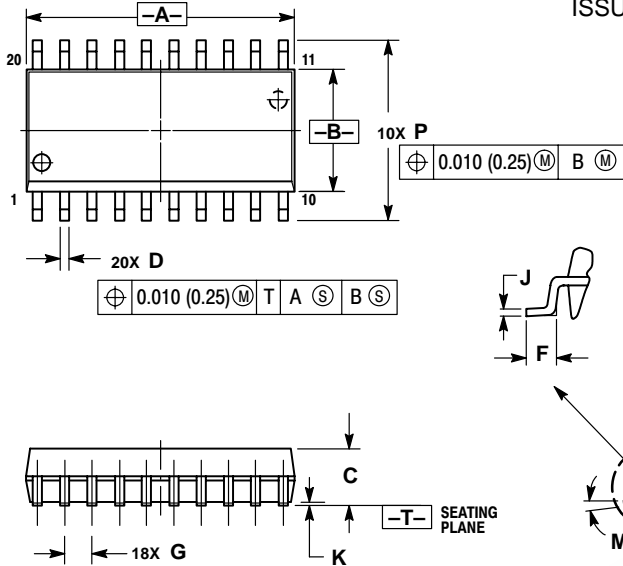
INPUT EQUIVALENT CIRCUIT



MC74LVX541

PACKAGE DIMENSIONS

SOIC-20 DW SUFFIX PLASTIC SOIC WIDE PACKAGE CASE 751D-05 ISSUE F

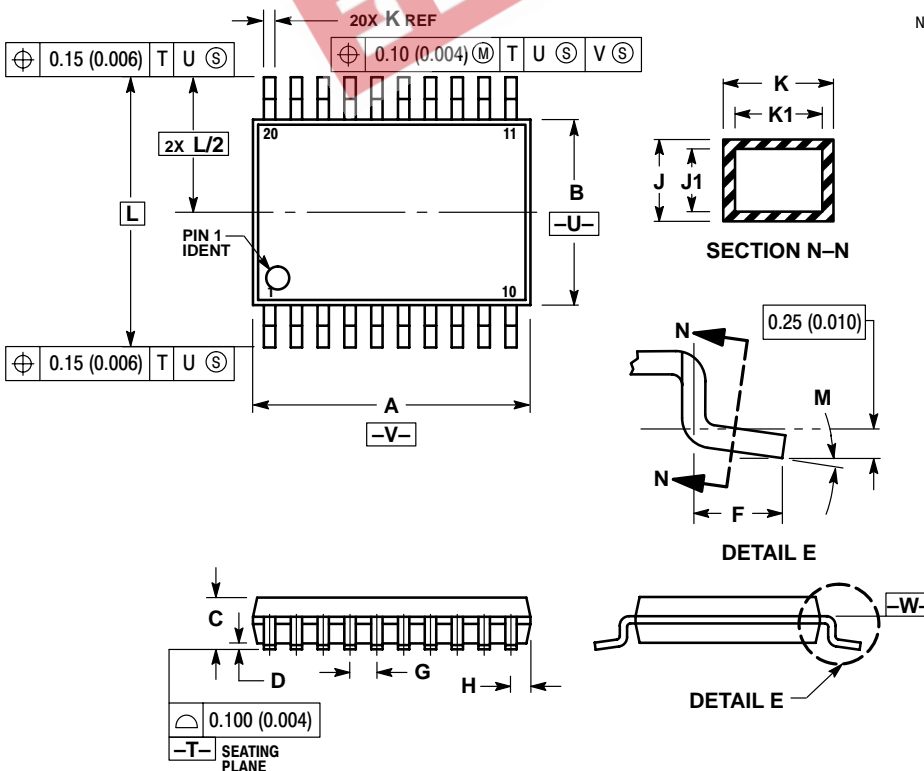


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.150 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|-------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 12.65 | 12.95 | 0.499 | 0.510 |
| B | 7.40 | 7.60 | 0.292 | 0.299 |
| C | 2.35 | 2.65 | 0.093 | 0.104 |
| D | 0.35 | 0.49 | 0.014 | 0.019 |
| F | 0.50 | 0.90 | 0.020 | 0.035 |
| G | 1.27 BSC | | 0.050 BSC | |
| J | 0.25 | 0.32 | 0.010 | 0.012 |
| K | 0.10 | 0.25 | 0.004 | 0.009 |
| M | 0° | 7° | 0° | 7° |
| P | 10.05 | 10.55 | 0.395 | 0.415 |
| R | 0.25 | 0.75 | 0.010 | 0.029 |

TSSOP-20 DT SUFFIX PLASTIC TSSOP PACKAGE CASE 948E-02 ISSUE A



NOTES:

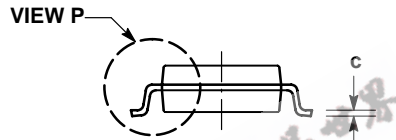
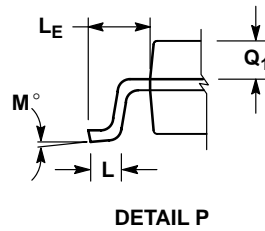
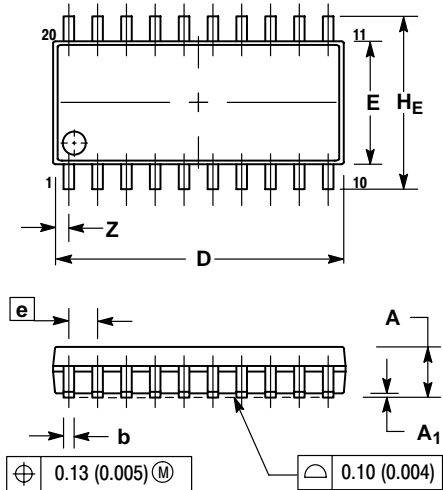
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 6.40 | 6.60 | 0.252 | 0.260 |
| B | 4.30 | 4.50 | 0.169 | 0.177 |
| C | --- | 1.20 | --- | 0.047 |
| D | 0.05 | 0.15 | 0.002 | 0.006 |
| F | 0.50 | 0.75 | 0.020 | 0.030 |
| G | 0.65 BSC | | 0.026 BSC | |
| H | 0.27 | 0.37 | 0.011 | 0.015 |
| J | 0.09 | 0.20 | 0.004 | 0.008 |
| J1 | 0.09 | 0.16 | 0.004 | 0.006 |
| K | 0.19 | 0.30 | 0.007 | 0.012 |
| K1 | 0.19 | 0.25 | 0.007 | 0.010 |
| L | 6.40 BSC | | 0.252 BSC | |
| M | 0° | 8° | 0° | 8° |

MC74LVX541

PACKAGE DIMENSIONS

SOIC EIAJ-20
M SUFFIX
PLASTIC SOIC EIAJ PACKAGE
CASE 967-01
ISSUE O




NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

| DIM | MILLIMETERS | | INCHES | |
|----------------|-------------|-------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | --- | 2.05 | --- | 0.081 |
| A ₁ | 0.05 | 0.20 | 0.002 | 0.008 |
| b | 0.35 | 0.50 | 0.014 | 0.020 |
| c | 0.18 | 0.27 | 0.007 | 0.011 |
| D | 12.35 | 12.80 | 0.486 | 0.504 |
| E | 5.10 | 5.45 | 0.201 | 0.215 |
| e | 1.27 BSC | | 0.050 BSC | |
| H _E | 7.40 | 8.20 | 0.291 | 0.323 |
| L | 0.50 | 0.85 | 0.020 | 0.033 |
| L _E | 1.10 | 1.50 | 0.043 | 0.059 |
| M | 0° | 10° | 0° | 10° |
| Q ₁ | 0.70 | 0.90 | 0.028 | 0.035 |
| Z | --- | 0.81 | --- | 0.032 |

MC74LVX541

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